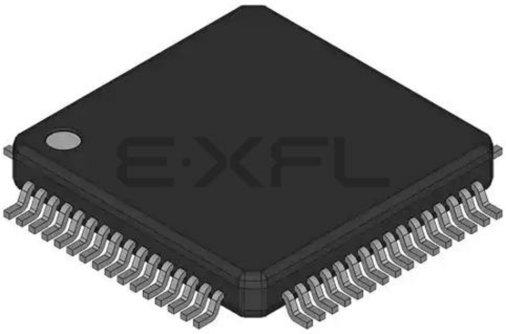
Freescale Semiconductor - MC9S08AW16MFUE Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-QFP
Supplier Device Package	64-QFP (14x14)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s08aw16mfue

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Section Number **Title** **Page**

Chapter 8
Internal Clock Generator (S08ICGV4)

Table 4-4. Nonvolatile Register Summary

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
$FFB0 – $FFB7	NVBACKKEY	8-Byte Comparison Key							
$FFB8 – $FFBB	Reserved	—	—	—	—	—	—	—	—
$FFBC	Reserved for storage of 250 kHz ICGTRM value	—	—	—	—	—	—	—	—
$FFBD	NVPROT	FPS7	FPS6	FPS5	FPS4	FPS3	FPS2	FPS1	FPDIS
$FFBE	Reserved for storage of 243 kHz ICGTRM value	—	—	—	—	—	—	—	—
$FFBF	NVOPT	KEYEN	FNORED	0	0	0	0	SEC01	SEC00

Provided the key enable (KEYEN) bit is 1, the 8-byte comparison key can be used to temporarily disengage memory security. This key mechanism can be accessed only through user code running in secure memory. (A security key cannot be entered directly through background debug commands.) This security key can be disabled completely by programming the KEYEN bit to 0. If the security key is disabled, the only way to disengage security is by mass erasing the FLASH if needed (normally through the background debug interface) and verifying that FLASH is blank. To avoid returning to secure mode after the next reset, program the security bits (SEC01:SEC00) to the unsecured state (1:0).

4.3 RAM

The MC9S08AW60 Series includes static RAM. The locations in RAM below $0100 can be accessed using the more efficient direct addressing mode, and any single bit in this area can be accessed with the bit manipulation instructions (BCLR, BSET, BRCLR, and BRSET). Locating the most frequently accessed program variables in this area of RAM is preferred.

The RAM retains data when the MCU is in low-power wait, stop2, or stop3 mode. At power-on, the contents of RAM are uninitialized. RAM data is unaffected by any reset provided that the supply voltage does not drop below the minimum value for RAM retention.

For compatibility with older M68HC05 MCUs, the HCS08 resets the stack pointer to $00FF. In the MC9S08AW60 Series, it is usually best to re-initialize the stack pointer to the top of the RAM so the direct page RAM can be used for frequently accessed RAM variables and bit-addressable program variables. Include the following 2-instruction sequence in your reset initialization routine (where RamLast is equated to the highest address of the RAM in the Freescale-provided equate file).

```
LDHX      #RamLast+1     ;point one past RAM
TXS                      ;SP<-(H:X-1)
```

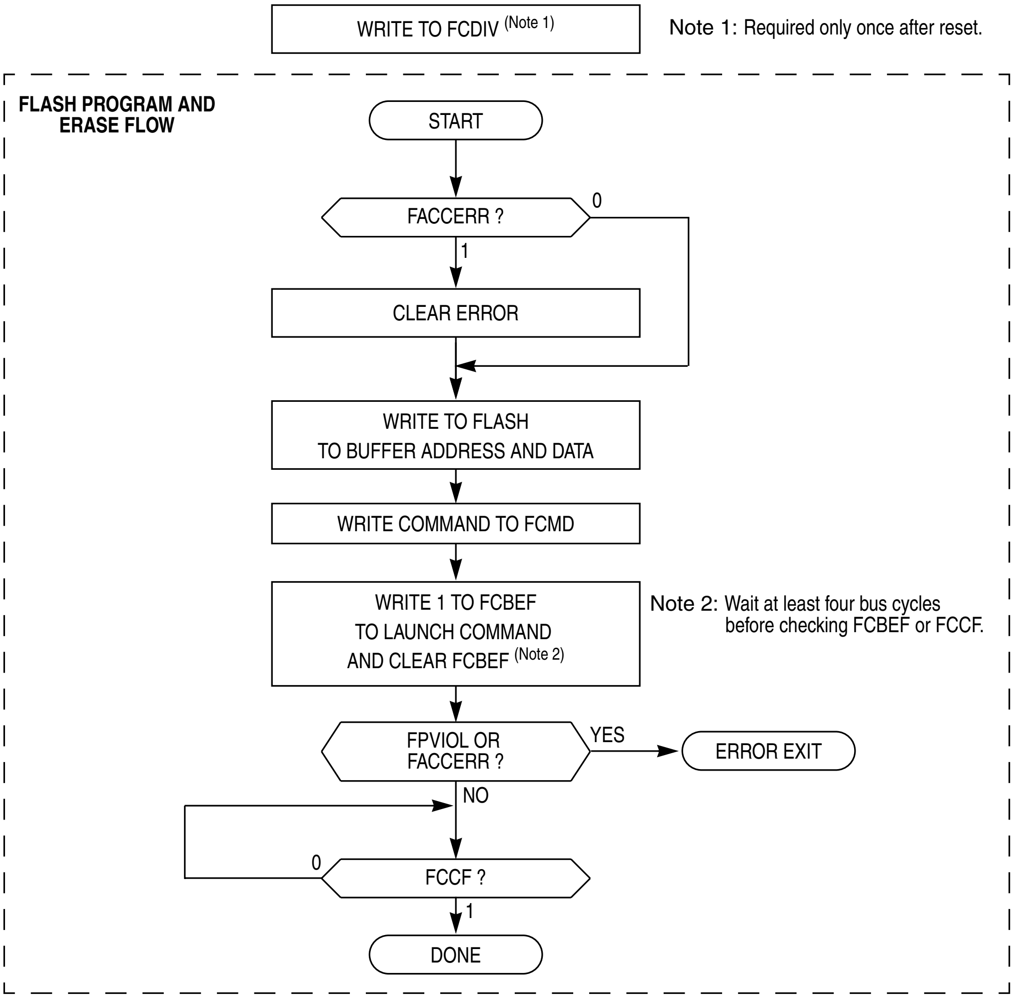


Figure 4-3. FLASH Program and Erase Flowchart

4.4.4 Burst Program Execution

The burst program command is used to program sequential bytes of data in less time than would be required using the standard program command. This is possible because the high voltage to the FLASH array does not need to be disabled between program operations. Ordinarily, when a program or erase command is issued, an internal charge pump associated with the FLASH memory must be enabled to supply high voltage to the array. Upon completion of the command, the charge pump is turned off. When a burst program command is issued, the charge pump is enabled and then remains enabled after completion of the burst program operation if these two conditions are met:

- The next burst program command has been queued before the current program operation has completed.
- The next sequential address selects a byte on the same physical row as the current byte being programmed. A row of FLASH memory consists of 64 bytes. A byte within a row is selected by addresses A5 through A0. A new row begins when addresses A5 through A0 are all zero.

I bit in the CCR is 0 to allow interrupts. The global interrupt mask (I bit) in the CCR is initially set after reset which masks (prevents) all maskable interrupt sources. The user program initializes the stack pointer and performs other system setup before clearing the I bit to allow the CPU to respond to interrupts.

When the CPU receives a qualified interrupt request, it completes the current instruction before responding to the interrupt. The interrupt sequence obeys the same cycle-by-cycle sequence as the SWI instruction and consists of:

- Saving the CPU registers on the stack
- Setting the I bit in the CCR to mask further interrupts
- Fetching the interrupt vector for the highest-priority interrupt that is currently pending
- Filling the instruction queue with the first three bytes of program information starting from the address fetched from the interrupt vector locations

While the CPU is responding to the interrupt, the I bit is automatically set to avoid the possibility of another interrupt interrupting the ISR itself (this is called nesting of interrupts). Normally, the I bit is restored to 0 when the CCR is restored from the value stacked on entry to the ISR. In rare cases, the I bit may be cleared inside an ISR (after clearing the status flag that generated the interrupt) so that other interrupts can be serviced without waiting for the first service routine to finish. This practice is not recommended for anyone other than the most experienced programmers because it can lead to subtle program errors that are difficult to debug.

The interrupt service routine ends with a return-from-interrupt (RTI) instruction which restores the CCR, A, X, and PC registers to their pre-interrupt values by reading the previously saved information off the stack.

NOTE

For compatibility with the M68HC08, the H register is not automatically saved and restored. It is good programming practice to push H onto the stack at the start of the interrupt service routine (ISR) and restore it immediately before the RTI that is used to return from the ISR.

When two or more interrupts are pending when the I bit is cleared, the highest priority source is serviced first (see Table 5-1).

5.5.1 Interrupt Stack Frame

Figure 5-1 shows the contents and organization of a stack frame. Before the interrupt, the stack pointer (SP) points at the next available byte location on the stack. The current values of CPU registers are stored on the stack starting with the low-order byte of the program counter (PCL) and ending with the CCR. After stacking, the SP points at the next available location on the stack which is the address that is one less than the address where the CCR was saved. The PC value that is stacked is the address of the instruction in the main program that would have executed next if the interrupt had not occurred.

	7	6	5	4	3	2	1	0
R W	PTEDS7	PTEDS6	PTEDS5	PTEDS4	PTEDS3	PTEDS2	PTEDS1	PTEDS0
Reset	0	0	0	0	0	0	0	0

Figure 6-33. Output Drive Strength Selection for Port E (PTEDS)

Table 6-26. PTEDS Register Field Descriptions

Field	Description
7:0 PTEDS[7:0]	**Output Drive Strength Selection for Port E Bits** — Each of these control bits selects between low and high output drive for the associated PTE pin. 0 Low output drive enabled for port E bit n. 1 High output drive enabled for port E bit n.

6.7.11 Port F I/O Registers (PTFD and PTFDD)

Port F parallel I/O function is controlled by the registers listed below.

	7	6	5	4	3	2	1	0
R W	PTFD7	PTFD6	PTFD5	PTFD4	PTFD3	PTFD2	PTFD1	PTFD0
Reset	0	0	0	0	0	0	0	0

Figure 6-34. Port F Data Register (PTFD)

Table 6-27. PTFD Register Field Descriptions

Field	Description
7:0 PTFD[7:0]	**Port F Data Register Bits**— For port F pins that are inputs, reads return the logic level on the pin. For port F pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port F pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTFD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pullups disabled.

	7	6	5	4	3	2	1	0
R W	PTFDD7	PTFDD6	PTFDD5	PTFDD4	PTFDD3	PTFDD2	PTFDD1	PTFDD0
Reset	0	0	0	0	0	0	0	0

Figure 6-35. Data Direction for Port F (PTFDD)

Table 6-28. PTFDD Register Field Descriptions

Field	Description
7:0 PTFDD[7:0]	**Data Direction for Port F Bits** — These read/write bits control the direction of port F pins and what is read for PTFD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port F bit n and PTFD reads return the contents of PTFDn.

7.3 Addressing Modes

Addressing modes define the way the CPU accesses operands and data. In the HCS08, all memory, status and control registers, and input/output (I/O) ports share a single 64-Kbyte linear address space so a 16-bit binary address can uniquely identify any memory location. This arrangement means that the same instructions that access variables in RAM can also be used to access I/O and control registers or nonvolatile program space.

Some instructions use more than one addressing mode. For instance, move instructions use one addressing mode to specify the source operand and a second addressing mode to specify the destination address. Instructions such as BRCLR, BRSET, CBEQ, and DBNZ use one addressing mode to specify the location of an operand for a test and then use relative addressing mode to specify the branch destination address when the tested condition is true. For BRCLR, BRSET, CBEQ, and DBNZ, the addressing mode listed in the instruction set tables is the addressing mode needed to access the operand to be tested, and relative addressing mode is implied for the branch destination.

7.3.1 Inherent Addressing Mode (INH)

In this addressing mode, operands needed to complete the instruction (if any) are located within CPU registers so the CPU does not need to access memory to get any operands.

7.3.2 Relative Addressing Mode (REL)

Relative addressing mode is used to specify the destination location for branch instructions. A signed 8-bit offset value is located in the memory location immediately following the opcode. During execution, if the branch condition is true, the signed offset is sign-extended to a 16-bit value and is added to the current contents of the program counter, which causes program execution to continue at the branch destination address.

7.3.3 Immediate Addressing Mode (IMM)

In immediate addressing mode, the operand needed to complete the instruction is included in the object code immediately following the instruction opcode in memory. In the case of a 16-bit immediate operand, the high-order byte is located in the next memory location after the opcode, and the low-order byte is located in the next memory location after that.

7.3.4 Direct Addressing Mode (DIR)

In direct addressing mode, the instruction includes the low-order eight bits of an address in the direct page (0x0000–0x00FF). During execution a 16-bit address is formed by concatenating an implied 0x00 for the high-order half of the address and the direct address from the instruction to get the 16-bit address where the desired operand is located. This is faster and more memory efficient than specifying a complete 16-bit address for the operand.

9.3.1 KBI Block Diagram

Figure 9-2 shows the block diagram for a KBI module.

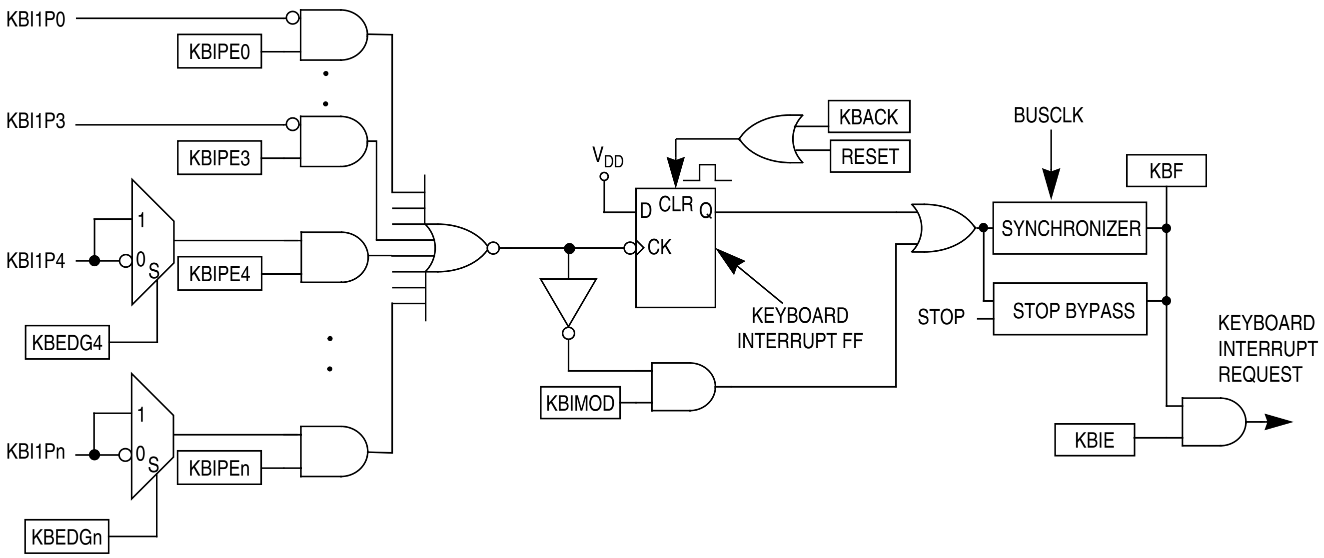


Figure 9-2. KBI Block Diagram

9.4 Register Definition

This section provides information about all registers and control bits associated with the KBI module.

Refer to the direct-page register summary in the Memory chapter of this data sheet for the absolute address assignments for all KBI registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

10.4.4 Timer x Channel n Status and Control Register (TPMxCnSC)

TPMxCnSC contains the channel interrupt status flag and control bits that are used to configure the interrupt enable, channel configuration, and pin function.

	7	6	5	4	3	2	1	0
R	CHnF	CHnIE	MSnB	MSnA	ELSnB	ELSnA	0	0
W							▨	▨
Reset	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 10-8. Timer x Channel n Status and Control Register (TPMxCnSC)

Table 10-4. TPMxCnSC Register Field Descriptions

Field	Description
7 CHnF	**Channel n Flag** — When channel n is configured for input capture, this flag bit is set when an active edge occurs on the channel n pin. When channel n is an output compare or edge-aligned PWM channel, CHnF is set when the value in the TPM counter registers matches the value in the TPM channel n value registers. This flag is seldom used with center-aligned PWMs because it is set every time the counter matches the channel value register, which correspond to both edges of the active duty cycle period. A corresponding interrupt is requested when CHnF is set and interrupts are enabled (CHnIE = 1). Clear CHnF by reading TPMxCnSC while CHnF is set and then writing a 0 to CHnF. If another interrupt request occurs before the clearing sequence is complete, the sequence is reset so CHnF would remain set after the clear sequence was completed for the earlier CHnF. This is done so a CHnF interrupt request cannot be lost by clearing a previous CHnF. Reset clears CHnF. Writing a 1 to CHnF has no effect. 0 No input capture or output compare event occurred on channel n 1 Input capture or output compare event occurred on channel n
6 CHnIE	**Channel n Interrupt Enable** — This read/write bit enables interrupts from channel n. Reset clears CHnIE. 0 Channel n interrupt requests disabled (use software polling) 1 Channel n interrupt requests enabled
5 MSnB	**Mode Select B for TPM Channel n** — When CPWMS = 0, MSnB = 1 configures TPM channel n for edge-aligned PWM mode. For a summary of channel mode and setup controls, refer to Table 10-5.
4 MSnA	**Mode Select A for TPM Channel n** — When CPWMS = 0 and MSnB = 0, MSnA configures TPM channel n for input capture mode or output compare mode. Refer to Table 10-5 for a summary of channel mode and setup controls.
3:2 ELSn[B:A]	**Edge/Level Select Bits** — Depending on the operating mode for the timer channel as set by CPWMS:MSnB:MSnA and shown in Table 10-5, these bits select the polarity of the input edge that triggers an input capture event, select the level that will be driven in response to an output compare match, or select the polarity of the PWM output. Setting ELSnB:ELSnA to 0:0 configures the related timer pin as a general-purpose I/O pin unrelated to any timer channel functions. This function is typically used to temporarily disable an input capture channel or to make the timer pin available as a general-purpose I/O pin when the associated timer channel is set up as a software timer that does not require the use of a pin.

If no new character is waiting in the transmit data buffer after a stop bit is shifted out the TxD pin, the transmitter sets the transmit complete flag and enters an idle mode, with TxD high, waiting for more characters to transmit.

Writing 0 to TE does not immediately release the pin to be a general-purpose I/O pin. Any transmit activity that is in progress must first be completed. This includes data characters in progress, queued idle characters, and queued break characters.

11.3.2.1 Send Break and Queued Idle

The SBK control bit in SCIxC2 is used to send break characters which were originally used to gain the attention of old teletype receivers. Break characters are a full character time of logic 0 (10 bit times including the start and stop bits). A longer break of 13 bit times can be enabled by setting BRK13 = 1. Normally, a program would wait for TDRE to become set to indicate the last character of a message has moved to the transmit shifter, then write 1 and then write 0 to the SBK bit. This action queues a break character to be sent as soon as the shifter is available. If SBK is still 1 when the queued break moves into the shifter (synchronized to the baud rate clock), an additional break character is queued. If the receiving device is another Freescale Semiconductor SCI, the break characters will be received as 0s in all eight data bits and a framing error (FE = 1) occurs.

When idle-line wakeup is used, a full character time of idle (logic 1) is needed between messages to wake up any sleeping receivers. Normally, a program would wait for TDRE to become set to indicate the last character of a message has moved to the transmit shifter, then write 0 and then write 1 to the TE bit. This action queues an idle character to be sent as soon as the shifter is available. As long as the character in the shifter does not finish while TE = 0, the SCI transmitter never actually releases control of the TxD pin. If there is a possibility of the shifter finishing while TE = 0, set the general-purpose I/O controls so the pin that is shared with TxD is an output driving a logic 1. This ensures that the TxD line will look like a normal idle line even if the SCI loses control of the port pin between writing 0 and then 1 to TE.

The length of the break character is affected by the BRK13 and M bits as shown below.

Table 11-8. Break Character Length

BRK13	M	Break Character Length
0	0	10 bit times
0	1	11 bit times
1	0	13 bit times
1	1	14 bit times

11.3.3 Receiver Functional Description

In this section, the receiver block diagram (Figure 11-3) is used as a guide for the overall receiver functional description. Next, the data sampling technique used to reconstruct receiver data is described in more detail. Finally, two variations of the receiver wakeup function are explained.

The receiver is enabled by setting the RE bit in SCIxC2. Character frames consist of a start bit of logic 0, eight (or nine) data bits (LSB first), and a stop bit of logic 1. For information about 9-bit data mode, refer

14.2.2.1 Analog Pin Enables

The ADC on MC9S08AW60 Series contains only two analog pin enable registers, APCTL1 and APCTL2.

14.2.2.2 Low-Power Mode Operation

The ADC is capable of running in stop3 mode but requires LVDSE and LVDE in SPMSC1 to be set.

14.2.3 Temperature Sensor

The ADC1 module includes a temperature sensor whose output is connected to one of the ADC analog channel inputs. Equation 14-1 provides an approximate transfer function of the temperature sensor.

$$\text{Temp} = 25 - ((V_{TEMP} - V_{TEMP25}) \div m) \qquad \textit{Eqn. 14-1}$$

where:

- V_{TEMP} is the voltage of the temperature sensor channel at the ambient temperature.
- V_{TEMP25} is the voltage of the temperature sensor channel at 25°C.
- m is the hot or cold voltage versus temperature slope in V/°C.

For temperature calculations, use the V_{TEMP25} and m values from the ADC Electricals table.

In application code, the user reads the temperature sensor channel, calculates V_{TEMP}, and compares to V_{TEMP25} . If V_{TEMP} is greater than V_{TEMP25} the cold slope value is applied in Equation 14-1. If V_{TEMP} is less than V_{TEMP25} the hot slope value is applied in Equation 14-1.

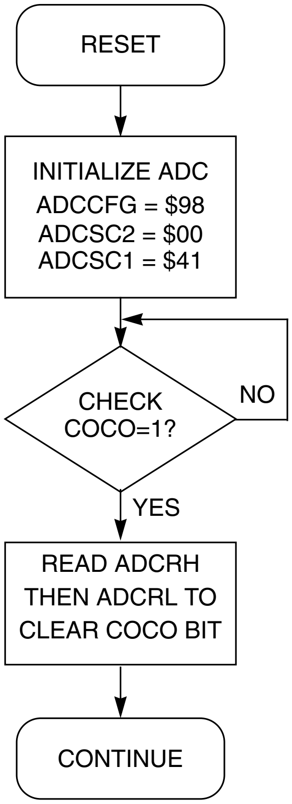


Figure 14-14. Initialization Flowchart for Example

14.7 Application Information

This section contains information for using the ADC module in applications. The ADC has been designed to be integrated into a microcontroller for use in embedded control applications requiring an A/D converter.

14.7.1 External Pins and Routing

The following sections discuss the external pins associated with the ADC module and how they should be used for best results.

14.7.1.1 Analog Supply Pins

The ADC module has analog power and ground supplies (V_{DDAD} and V_{SSAD}) which are available as separate pins on some devices. On other devices, V_{SSAD} is shared on the same pin as the MCU digital V_{SS}, and on others, both V_{SSAD} and V_{DDAD} are shared with the MCU digital supply pins. In these cases, there are separate pads for the analog supplies which are bonded to the same pin as the corresponding digital supply so that some degree of isolation between the supplies is maintained.

When available on a separate pin, both V_{DDAD} and V_{SSAD} must be connected to the same voltage potential as their corresponding MCU digital supply (V_{DD} and V_{SS}) and must be routed carefully for maximum noise immunity and bypass capacitors placed as near as possible to the package.

15.3.6 Hardware Breakpoints

The BRKEN control bit in the DBGC register may be set to 1 to allow any of the trigger conditions described in Section 15.3.5, “Trigger Modes,” to be used to generate a hardware breakpoint request to the CPU. TAG in DBGC controls whether the breakpoint request will be treated as a tag-type breakpoint or a force-type breakpoint. A tag breakpoint causes the current opcode to be marked as it enters the instruction queue. If a tagged opcode reaches the end of the pipe, the CPU executes a BGND instruction to go to active background mode rather than executing the tagged opcode. A force-type breakpoint causes the CPU to finish the current instruction and then go to active background mode.

If the background mode has not been enabled (ENBDM = 1) by a serial WRITE_CONTROL command through the BKGD pin, the CPU will execute an SWI instruction instead of going to active background mode.

15.4 Register Definition

This section contains the descriptions of the BDC and DBG registers and control bits.

Refer to the high-page register summary in the device overview chapter of this data sheet for the absolute address assignments for all DBG registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

15.4.1 BDC Registers and Control Bits

The BDC has two registers:

- The BDC status and control register (BDCSCR) is an 8-bit register containing control and status bits for the background debug controller.
- The BDC breakpoint match register (BDCBKPT) holds a 16-bit breakpoint match address.

These registers are accessed with dedicated serial BDC commands and are not located in the memory space of the target MCU (so they do not have addresses and cannot be accessed by user programs).

Some of the bits in the BDCSCR have write limitations; otherwise, these registers may be read or written at any time. For example, the ENBDM control bit may not be written while the MCU is in active background mode. (This prevents the ambiguous condition of the control bit forbidding active background mode while the MCU is already in active background mode.) Also, the four status bits (BDMACT, WS, WSF, and DVF) are read-only status indicators and can never be written by the WRITE_CONTROL serial BDC command. The clock switch (CLKSW) control bit may be read or written at any time.

Table 15-2. BDCSCR Register Field Descriptions (continued)

Field	Description
2 WS	**Wait or Stop Status** — When the target CPU is in wait or stop mode, most BDC commands cannot function. However, the BACKGROUND command can be used to force the target CPU out of wait or stop and into active background mode where all BDC commands work. Whenever the host forces the target MCU into active background mode, the host should issue a READ_STATUS command to check that BDMACT = 1 before attempting other BDC commands. 0 Target CPU is running user application code or in active background mode (was not in wait or stop mode when background became active) 1 Target CPU is in wait or stop mode, or a BACKGROUND command was used to change from wait or stop to active background mode
1 WSF	**Wait or Stop Failure Status** — This status bit is set if a memory access command failed due to the target CPU executing a wait or stop instruction at or about the same time. The usual recovery strategy is to issue a BACKGROUND command to get out of wait or stop mode into active background mode, repeat the command that failed, then return to the user program. (Typically, the host would restore CPU registers and stack values and re-execute the wait or stop instruction.) 0 Memory access did not conflict with a wait or stop instruction 1 Memory access command failed because the CPU entered wait or stop mode
0 DVF	**Data Valid Failure Status** — This status bit is not used in the MC9S08AW60 Series because it does not have any slow access memory. 0 Memory access did not conflict with a slow memory access 1 Memory access command failed because CPU was not finished with a slow memory access

15.4.1.2 BDC Breakpoint Match Register (BDCBKPT)

This 16-bit register holds the address for the hardware breakpoint in the BDC. The BKPTEN and FTS control bits in BDCSCR are used to enable and configure the breakpoint logic. Dedicated serial BDC commands (READ_BKPT and WRITE_BKPT) are used to read and write the BDCBKPT register but is not accessible to user programs because it is not located in the normal memory map of the MCU. Breakpoints are normally set while the target MCU is in active background mode before running the user application program. For additional information about setup and use of the hardware breakpoint logic in the BDC, refer to Section 15.2.4, “BDC Hardware Breakpoint.”

15.4.2 System Background Debug Force Reset Register (SBDFR)

This register contains a single write-only control bit. A serial background mode command such as WRITE_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.

Table A-2. Absolute Maximum Ratings

Rating	Symbol	Value	Unit
Supply voltage	V_{DD}	–0.3 to + 5.8	V
Input voltage	V_{In}	– 0.3 to V_{DD} + 0.3	V
Instantaneous maximum current Single pin limit (applies to all port pins)[1], [2], [3]	I_D	± 25	mA
Maximum current into V_{DD}	I_{DD}	120	mA
Storage temperature	T_{stg}	–55 to +150	°C
Maximum junction temperature	T_J	150	°C

[1] Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive (V_{DD}) and negative (V_{SS}) clamp voltages, then use the larger of the two resistance values.

[2] All functional non-supply pins are internally clamped to V_{SS} and V_{DD}.

[3] Power supply must maintain regulation within operating V_{DD} range during instantaneous and operating maximum current conditions. If positive injection current ($V_{In} > V_{DD}$) is greater than I_{DD}, the injection current may flow out of V_{DD} and could result in external power supply going out of regulation. Ensure external V_{DD} load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power. Examples are: if no system clock is present, or if the clock rate is very low which would reduce overall power consumption.

Table A-12. ICG Frequency Specifications (continued)

(V_{DDA} = V_{DDA} (min) to V_{DDA} (max), Temperature Range = –40 to 125°C Ambient)

Num	C	Characteristic	Symbol	Min	Typ[1]	Max	Unit
19	**MC9S08AW*xx*:** Internal oscillator deviation from trimmed frequency[9]						
	C	V_{DD} = 2.7 – 5.5 V, (constant temperature)	ACC_{int}	—	±0.5	±2	%
	P	V_{DD} = 5.0 V ±10%, –40° C to 125°C		—	±0.5	±2	%
	S9S08AW*xx*: Internal oscillator deviation from trimmed frequency[9]						
	C	V_{DD} = 2.7 – 5.5 V, (constant temperature)	ACC_{int}	—	±0.5	±1.5	%
	P	V_{DD} = 5.0 V ±10%, –40° C to 85°C		—	±0.5	±1.5	%
	P	V_{DD} = 5.0 V ±10%, –40° C to 125°C		—	±0.5	±2	%

[1] Typical values are based on characterization data at V_{DD} = 5.0V, 25°C unless otherwise stated.

[2] Self-clocked mode frequency is the frequency that the DCO generates when the FLL is open-loop.

[3] Loss of reference frequency is the reference frequency detected internally, which transitions the ICG into self-clocked mode if it is not in the desired range.

[4] Loss of DCO frequency is the DCO frequency detected internally, which transitions the ICG into FLL bypassed external mode (if an external reference exists) if it is not in the desired range.

[5] This parameter is characterized before qualification rather than 100% tested.

[6] Proper PC board layout procedures must be followed to achieve specifications.

[7] This specification applies to the period of time required for the FLL to lock after entering FLL engaged internal or external modes. If a crystal/resonator is being used as the reference, this specification assumes it is already running.

[8] Jitter is the average deviation from the programmed frequency measured over the specified interval at maximum f_{ICGOUT}. Measurements are made with the device powered by filtered supplies and clocked by a stable external clock signal. Noise injected into the FLL circuitry via V_{DDA} and V_{SSA} and variation in crystal oscillator frequency increase the C_{Jitter} percentage for a given interval.

[9] See Figure A-9.

Appendix B
Ordering Information and Mechanical Drawings

B.1 Ordering Information

This section contains ordering numbers for MC9S08AW60 Series devices. See below for an example of the device numbering system.

Table B-1. *Consumer and Industrial* Device Numbering System

Device Number[1]	Memory		Available Packages[2]
	FLASH	RAM	Type
MC9S08AW60 MC9S08AW48 MC9S08AW32	63,280 49,152 32,768	2048	64-pin LQFP 64-pin QFP 48-pin QFN 44-pin LQFP
MC9S08AW16	16,384	1024	

[1] See Table 1-1 for a complete description of modules included on each device.

[2] See Table B-3 for package information.

Table B-2. *Automotive* Device Numbering System

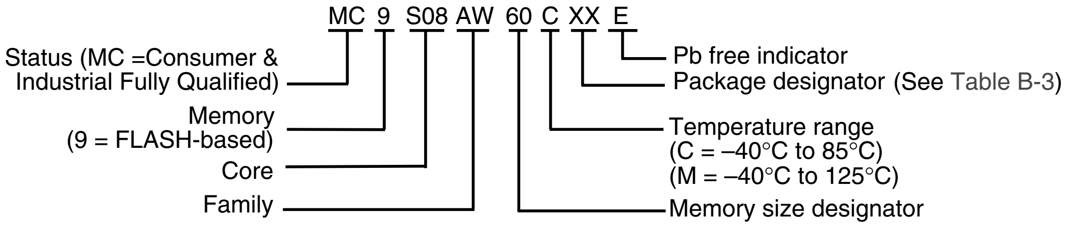
Device Number[1]	Memory		Available Packages[2]
	FLASH	RAM	Type
S9S08AW60 S9S08AW48 S9S08AW32	63,280 49,152 32,768	2048	64-pin LQFP 48-pin QFN 44-pin LQFP
S9S08AW16	16,384	1024	48-pin QFN 44-pin LQFP

[1] See Table 1-1 for a complete description of modules included on each device.

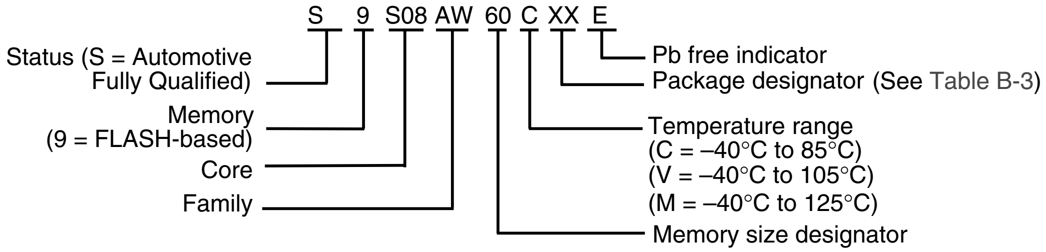
[2] See Table B-3 for package information.

B.2 Orderable Part Numbering System

B.2.1 Consumer and Industrial Orderable Part Numbering System



B.2.2 Automotive Orderable Part Numbering System



B.3 Mechanical Drawings

This following pages contain mechanical specifications for MC9S08AW60 Series package options. See Table B-3 for the document numbers that correspond to each package type.

Table B-3. Package Information

Pin Count	Type	Designator	Document No.
44	LQFP	FG	98ASS23225W
48	QFN	FD	98ARH99048A
64	LQFP	PU	98ASS23234W
64	QFP	FU	98ASB42844B